



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

Datum:

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01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 169 FR4 55_70 L71.70 P18 S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_169_FR4_55_70_L71.70_p18_s1

Layers	in μ	Material	Build-Up	Assembly
Layer-1	55 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-2	70 μ	Copper		
	710 μ	L-FR4		
Layer-3	70 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-99	70 μ	Copper		

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